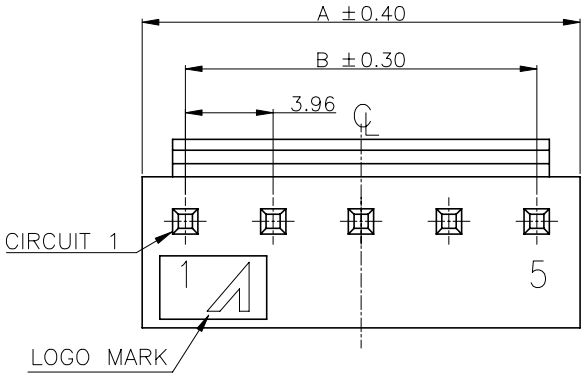
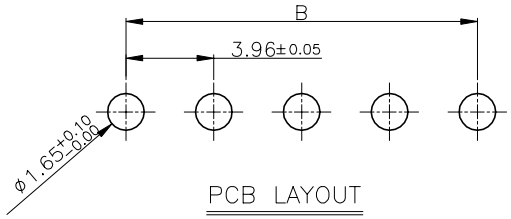




PCB LAYOUT

NOTES:
1. MATERIAL:
   1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0;
   1.2 CONTACT: COPPER ALLOY
2. FINISH:
   2.1 CONTACT:
   N: 50~100u" MATTE TIN PLATING OVERALL
   50u" MIN. NICKEL UNDERPLATING OVERALL
3. SPEC. PLS. REFER TO PS-51281-xxxxx-xxx
4. PART NUMBER

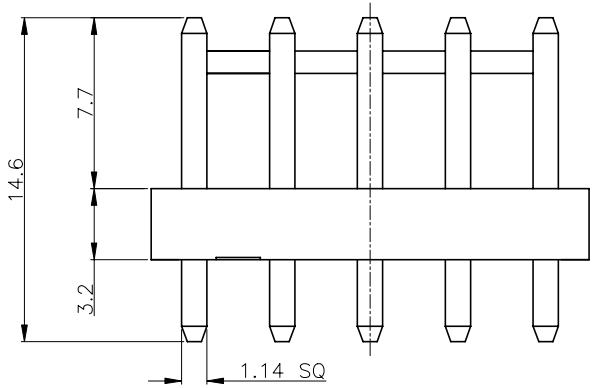
51281-XXX X X-XXX

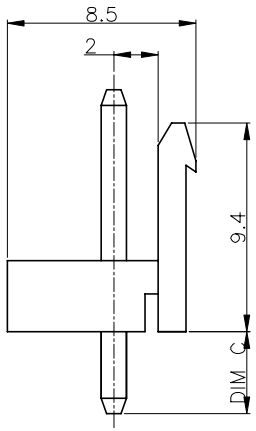
NO OF CKT

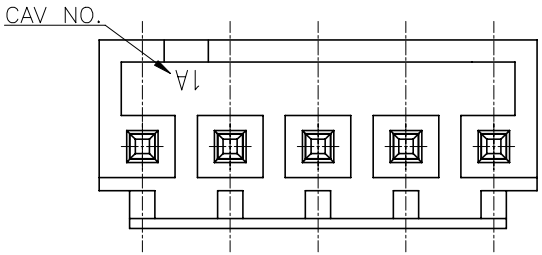
PACKING
3:BAG

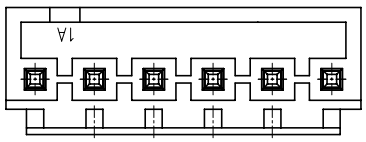
PLATING
N: MATTE TIN PLATING OVERALL

XXX	HOUSING	DIM C	VOID CKT
001	PA66 PLASTIC&NATURAL	3.70	NA
020	PA66PLASTIC&NATURAL	3.70	空第 2PIN
024	PA66 PLASTIC&NATURAL	3.70	空第 2/4PIN
002	PA66 PLASTIC&BLACK	3.70	NA
003	LCP&NATURAL	3.70	空第 2PIN

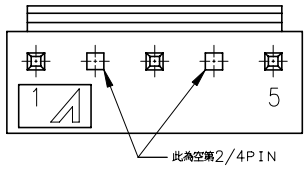


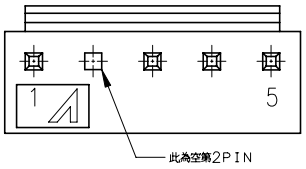


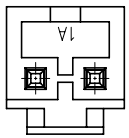


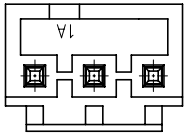


CKT	Dim A	Dim B
2	7.86	3.96
3	11.82	7.92
4	15.78	11.88
5	19.74	15.84
6	23.70	19.80









QUALITY SYMBOLS MAJOR Ⓜ CRITICAL Ⓒ	DRAWN BY Huang,Shun Sen	DATE 23'/08/18	ACES ELECTRONICS
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	CHECKED BY Lu,Jing Quan	DATE 23'/08/18	TITLE 3.96mm WTB WAFER CONN. T/H S/T TYPE
	APPROVED BY hsieh,fu yu	DATE 23'/08/18	
	UNITS mm	SIZE A4	RFQ NO. N/A
	SCALE 3 : 1	SHEET NO. 1 OF 1	REV D	DWG NO. 51281-XXXXX-XXX

2018.10.25_REV.11